

## IN THE SPECIFICATION

Please replace the paragraph beginning at p. 25, line 24, with the following paragraph:

Next, the mirror element 1 is connected to the optical substrate 2. As shown in Fig. 8A, connection pads 15 for the mirror element 1 are formed on the optical circuit substrate 2 by a gold plating method. Besides, a groove 16 for fixing an optical fiber and optical element connection electrodes 17 are formed. The optical circuit substrate 2 and the silicon wafer 5 on which the Au films 14 are formed are adjusted in position by a connection unit (not shown). After that, the Au films 14 are connected to the optical circuit substrate 2 under the condition of the temperature of 370°C and the pressure of 1 N/cm<sup>2</sup> (100 g Weight/cm<sup>2</sup>). Then, the silicon wafer 5 is lifted up. At this time, the copper film 12 is peeled from the silicon wafer die 5. The mirror element 1 remains on the optical circuit substrate 2 in a state in which the mirror element 1 is covered by the copper film 12. Fig 8B shows the mirror element 1 after the movement onto the optical circuit substrate 2. Fig. 9A is a plan view showing the mirror element 1 after the mount, and Fig. [[5]]9B is a front view showing the mirror element 1. The mirror element 1 has the shape that both upper ends of a triangular-prism shape in an axis direction a are cut away in a slant direction.